

Honorary General Chairs Yeong-Her Wang Dong-Sing Wuu Hsiu-Shuang Huang Mau-Phon Houng **General Chairs** Chien-Jung Huang Herchang Ay Tai-Ping Sun Ming-Chung Ho **General Co-Chairs** Juing-Shian Chiou **Te-Kuang Chiang** Wen-Kuan Yeh Chuan-Hsi Liu **Bao-Rong Chang** Meng-Chyi Wu Chao Sung Lai Chao-Hsin Wu Ray Hua Houng **Tsair-Chun Liang Technical Program Chairs** Jung Chuan Chou Te-Jen Su Kuan-Wei Lee Shih-Wei Feng Ming-Chuan Wang **Advisory Committee** Daqing Zhu Jun Zhu Huang Dou Fei Yu Kuan Chee Wencheng Yu Yang Li Takao Someya

Submission of Papers

Frank Schwierz

Prospective authors with accepted abstracts will be invited to submit their extended manuscripts to SCI or SSCI Journals recommended by the program committees of ICSEVEN 2019. Technical papers on the aspects related to (but not limited to) those in the topics of interest are invited for oral or poster presentation.

http://www.taai.tw/icseven/submission/ptid/5.html

Excellent papers will be recommended to be published on different SCI or SSCI journals after an additional review process and may need extra publication charge.

1.Neurocomputing (ISSN 0925-2312; IF:3.24; SCI)

- 2.Computers & Industrial Engineering (ISSN 0360-8352; IF:3.19; SCI)
- 3.Materials (ISSN 1996-1944; IF:2.73; SCI)
- 4.Energies (ISSN 1996-1073; IF:2.08; SCI)
- 5.Crystals (ISSN 2073-4352; IF:2.14; SCI)
- 6.Applied Soft Computing (ISSN 1568-4946; IF:3.91; SCI)

7.International Journal of Science and Mathematics Education (ISSN 1571-0068; IF:1.10; SSCI)

- 8.International Journal of Engineering Education (ISSN 0949-149X; IF: 0.609; SCIE)
- 9.Sensors and Materials (ISSN 0914-4935; IF: 0.49; SCI)

10.International Journal of Electrical Engineering Education (ISSN 0020-7209; IF=0.302; SCIE)

The 4th International Conference 2019 on
Science, Education and Viable EngineeringCall for Papers

http://www.taai.tw/icseven/

Ho Chi Minh, Vietnam Apr. 6-10, 2019



The 4th International Conference on Science, Education and Viable Engineering (4th ICSEVEN-2019) organized in cooperation with IEEE and Lac Hong University is a communication platform for scholars, researchers and practitioners to discuss interdisciplinary research and practices in the fields of Engineering, Science, Education, Management of Global Resources, Cultures, and emerging disciplines. The aim of the conference is to share and learn from experiences made in different education systems all over the world and to find out about the core elements leading to successful learning, implementation, and business opportunities. Topics of interest include, but are not limited to the following:

- (A) Material Science and Engineering;
- (B) Microelectronics;
- (C) Computational Science and Engineering;
- (D) Electrical Engineering;
- (E) Mechanical and Automation Engineering;
- (F) Innovation and Creative Design;
- (G) Cultural and Creative Research;
- (H) Management Science;
- (I) Education and Teaching Research;
- (J) STEM Education and Teaching Aid;
- (K) Others.





Ho Chi Minh City (commonly known as Saigon) is the most populous city and the important center of economy, culture and education in southern Vietnam. On the basis of the existing urban area, Ho Chi Minh City is the Vietnam's largest city. Currently, Ho Chi Minh City and Hanoi are special kinds of urban in Vietnam.

Deadlines

Submission due date:	Feb. 12, 2019
Notification of Abstract Acceptance:	Feb. 15, 2019
Early registration due date:	Feb. 20, 2019
Conference date:	Apr. 6-10, 2019

